



100V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BVDSS	R _{DS(ON)} max	I _D max T _A = +25°C
400)/	$32m\Omega$ @ $V_{GS} = 10V$	6A
100V	46mΩ @ V _{GS} = 4.5V	5A

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

Applications

- **Power Management Functions**
- Battery Operated Systems and Solid-State Relays
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories, Transistors, etc.

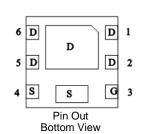
U-DFN2020-6 (Type F) Pin1 Top View **Bottom View**

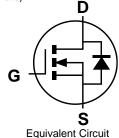
Features and Benefits

- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm²
- Low On-Resistance
- 100% Unclamped Inductive Switching (UIS) Test in Production -Ensures More Reliable and Robust End Application
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Mechanical Data

- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @4
- Weight: 0.0065 grams (Approximate)





Ordering Information (Note 4)

Part Number	Case	Quantity Per Reel		
DMT10H032LFDF-7	U-DFN2020-6 (Type F)	3,000		
DMT10H032LFDF-13	U-DFN2020-6 (Type F)	10,000		

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

U-DFN2020-6 (Type F)



32 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 0 = 2020)

W = Week (ex: a = week 27; z represents week 52 and 53)

X = Internal Code (ex: U = Monday)

Date Code Key					_							
Year	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030
Code	9	0	1	2	3	4	5	6	7	8	9	0
Week	Week 1-26			I	27-52 53							
	1-20					21	-J2		JJ			
Code		F	\-Z			a	-Z			Z	7	
Internal Code	Sun	1	Mon		Tue	W	ed	Thu		Fri		Sat
Code	Т		U		V	V	٧	X		Υ		Z

DMT10H032LFDF Datasheet number: DS41972 Rev. 2 - 2



Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	VDSS	100	V	
Gate-Source Voltage	V_{GSS}	±20	V	
Continuous Drain Current, V _{GS} = 10V (Note 6)	ΔI	6 5	А	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		I _{DM}	40	Α
Maximum Body Diode Continuous Current	Is	6	Α	
Pulsed Body Diode Current (10µs Pulse, Duty Cycle = 1%)	Ism	40	Α	
Avalanche Current, L = 0.3mH (Note 9)	las	13	Α	
Avalanche Energy, L = 0.3mH (Note 9)	E _{AS}	25.3	mJ	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T _A = +25°C	6	1.3	W
Total Fower Dissipation (Note 5)	T _A = +70°C	PD	0.8	VV
Thermal Resistance, Junction to Ambient (Note 5)	R _θ JA	94.5	°C/W	
Total Power Dissipation (Note 6)	T _A = +25°C		1.6	W
Total Power Dissipation (Note 6)	$T_A = +70$ °C	P_{D}	1.1	VV
Thermal Resistance, Junction to Ambient (Note 6)	$R_{ heta JA}$	75.2	°C/W	
Thermal Resistance, Junction to Case (Note 6)	Rелс	9.2	C/VV	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

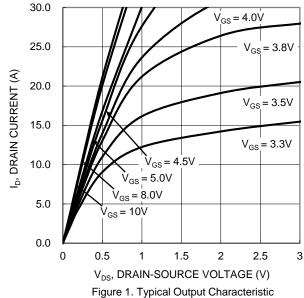
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 7)								
Drain-Source Breakdown Voltage	BVDSS	100	_	_	V	$V_{GS} = 0V, I_D = 1mA$		
Zero Gate Voltage Drain Current	I _{DSS}	_	-	1	μΑ	$V_{DS} = 80V, V_{GS} = 0V$		
Gate-Source Leakage	Igss	_	-	±100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$		
ON CHARACTERISTICS (Note 7)								
Gate Threshold Voltage	VGS(TH)	1.3	_	2.5	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$		
Static Drain-Source On-Resistance	D	_	24	32	mΩ	Vgs = 10V, ID = 6A		
Static Drain-Source On-Resistance	R _{DS(ON)}	_	33	46	11177	Vgs = 4.5V, ID = 4A		
Diode Forward Voltage	VsD	_	0.8	1.0	V	V _G S = 0V, I _S = 6A		
DYNAMIC CHARACTERISTICS (Note 8)								
Input Capacitance	Ciss	1	683	_	pF	., 50,4,4, 0,4		
Output Capacitance	Coss	-	165	_	pF	$V_{DS} = 50V, V_{GS} = 0V,$ f = 1MHz		
Reverse Transfer Capacitance	Crss	_	6.9	_	pF	1 = 1101112		
Gate Resistance	Rg	_	1.2	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$		
Total Gate Charge (VGS = 4.5V)	Qg	_	6.3	_	nC			
Total Gate Charge (V _{GS} = 10V)	Qg	_	11.9	_	nC) 		
Gate-Source Charge	Qgs	_	2.0	_	nC	$V_{DS} = 50V, I_{D} = 6A$		
Gate-Drain Charge	Qgd	_	3.1	_	nC	1		
Turn-On Delay Time	td(on)	_	4.1	_	ns			
Turn-On Rise Time	t _R	_	4.5	_	ns	$V_{DS} = 50V, R_{L} = 5.85\Omega$		
Turn-Off Delay Time	tD(OFF)	_	12.5	_	ns	$V_{GS} = 10V, R_{GEN} = 3\Omega$		
Turn-Off Fall Time	tF		9.3	_	ns]		
Reverse Recovery Time	trr	_	31.5	_	ns	I		
Reverse Recovery Charge	Q _{RR}		94.6	_	nC	I _F = 6A, di/dt = 500A/μs		

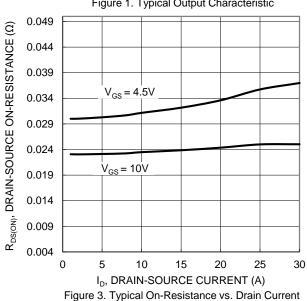
Notes:

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to product testing.
- 9. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.

2 of 7 DMT10H032LFDF March 2020 © Diodes Incorporated Datasheet number: DS41972 Rev. 2 - 2







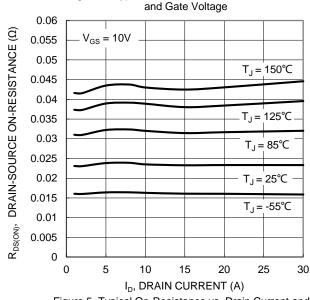


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

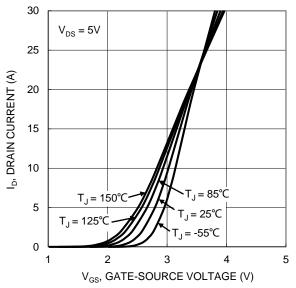
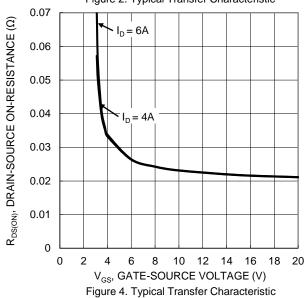


Figure 2. Typical Transfer Characteristic



2.2 R_{DS(ON)}, DRAIN-SOURCE ON-RESISTANCE 2 $V_{GS} = 10V, I_{D} = 6A$ 1.8 (NORMALIZED) 1.6 1.4 1.2 $V_{GS} = 4.5V, I_{D} = 4A$ 1 8.0 0.6 -50 25 50 75 100 125 150 T_J, JUNCTION TEMPERATURE (°C)

Figure 6. On-Resistance Variation with Junction Temperature





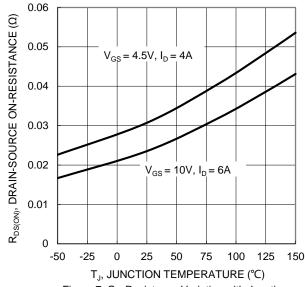
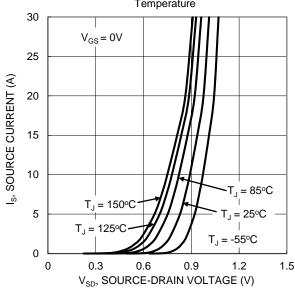


Figure 7. On-Resistance Variation with Junction Temperature



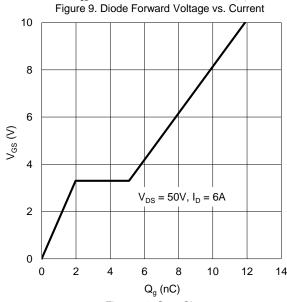


Figure 11. Gate Charge

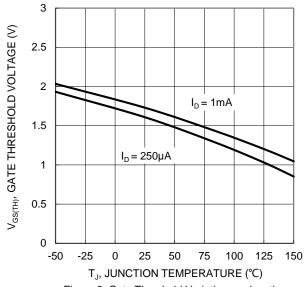
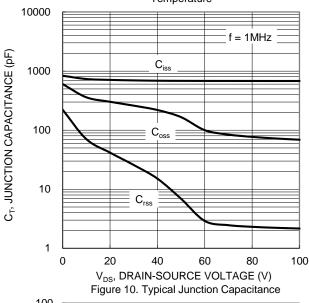


Figure 8. Gate Threshold Variation vs. Junction Temperature



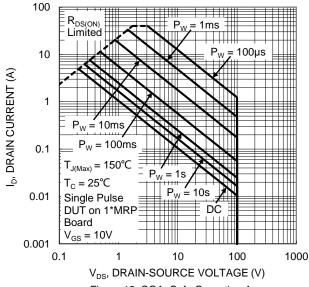


Figure 12. SOA, Safe Operation Area



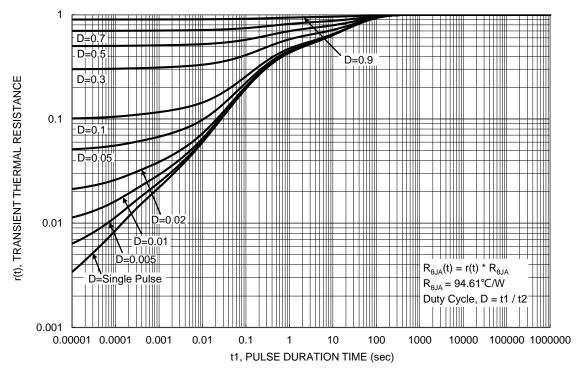


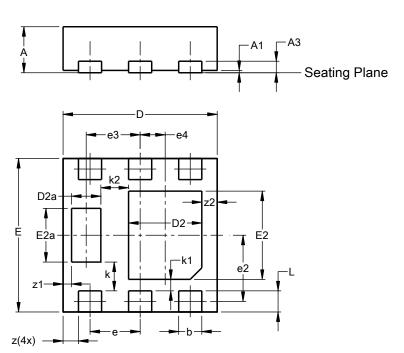
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)

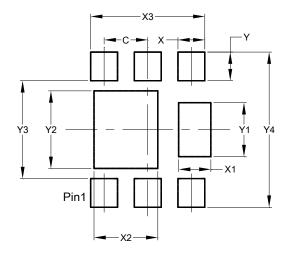


U-DFN2020-6								
(Type F)								
Dim	Min Max Typ							
Α	0.57 0.63 0.60							
A1	0.00 0.05 0.03							
A3	-	-	0.15					
b	0.25	0.35	0.30					
D	1.95	2.05	2.00					
D2	0.85	1.05	0.95					
D2a	0.33	0.43	0.38					
Е	1.95	2.05	2.00					
E2	1.05	1.25	1.15					
E2a	0.65 0.75 0.70							
е	0.65 BSC							
e2	0.863 BSC							
е3	0.70 BSC							
e4	0.325 BSC							
k	0.37 BSC							
k1	0.15 BSC							
k2	0.36 BSC							
L	0.225 0.325 0.275							
Z	0.20 BSC							
z 1	0.110 BSC							
z2	0.20 BSC							
All Dimensions in mm								

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)



Dimensions	Value (in mm)		
С	0.650		
Х	0.400		
X1	0.480		
X2	0.950		
Х3	1.700		
Y	0.425		
Y1	0.800		
Y2	1.150		
Y3	1.450		
Y4	2.300		



IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2020, Diodes Incorporated

www.diodes.com

DMT10H032LFDF 7 of 7 March 2020

Datasheet number: DS41972 Rev. 2 - 2

© Diodes Incorporated

单击下面可查看定价,库存,交付和生命周期等信息

>>Diodes Incorporated(达迩科技(美台))